

**U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE**

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ALLEG-039PUS

APPLICATION NO.
10/649,450

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

APPLICANT
Michael Doogue, et al.

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August 26, 2003

GROUP
2831

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPROPRIATE*

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)

		EP Office Action dated June 17, 2009; for EP Pat. App. No. 048163162.4 (Atty. Dckt. No. ALLEG-039PEP)
		Lee et al.; "Fine Pitch Au-SnAgCu Joint-in-via Flip-Chip Packaging;" IEEE 9 th Electronics Packaging Technology Conference, December 10-12, 2007; Pages 1-7
Examiner		Date Considered:
		*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and considered. Include copy of this form with next communication to applicant.